#### 508044313 08/02/2023

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
NORBERT L. KUKTA	08/01/2023

# **RECEIVING PARTY DATA**

Name:	HONDA MOTOR CO., LTD.
Street Address:	NO. 1-1, MINAMI-AOYAMA 2-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN

# **PROPERTY NUMBERS Total: 1**

Property Type	Number	
Application Number:	17559294	

## CORRESPONDENCE DATA

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KENEALY VAIDYA LLP HONDA **Correspondent Name:** 

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ATTORNEY DOCKET NUMBER:	3009-0383
NAME OF SUBMITTER:	WILLIAM G. BATTISTA, JR.
SIGNATURE:	/w.g.battista/
DATE SIGNED:	08/02/2023

## **Total Attachments: 2**

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> **PATENT REEL: 064463 FRAME: 0439** 508044313

#### ASSIGNMENT

WHEREAS WE, the below named inventors, [hereinafter referred to as Assignors], have made an invention entitled:

# APPARATUS, KIT AND METHOD FOR SIMULATING A VEHICLE SURFACE AND MAPPING A SPRAY PATTERN OF A WATER LEAK TESTER

for which WE executed an application for United States Letters Patent concurrently herewith; and

WHEREAS <u>Honda Motor Co., Ltd.</u>, a corporation of <u>Japan</u>, whose post office address is <u>No. 1-1</u>, <u>Minami-Aoyama 2-chome</u>, <u>Minato-ku</u>, <u>Tokyo</u>, <u>Japan</u> (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for and in consideration of good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND. WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys empowered by Honda Motor Co., Ltd. in this application, to insert here in parentheses (Application No. <u>17/559.294</u>, filed <u>December 22</u>, <u>2021</u>) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

KENEALY VAIDYA LLP

PATENT REEL: 064463 FRAME: 0440

ATTORNEY DOCKET NO.: 3009-0383 U.S. Patent Application No.: 17/559,294

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Full Name of First Assignor Muhammad ARHAM	Assignor's Signature	Date			
Address; c/o American Honda Motor Co., Inc. 21001 State Route 739, Raymond, Ohio 43067-9705					
Full Name of Second Assignor Timothy Brien SIROLA	Assignor's Signature	Date:			
Address: c/o American Honda Motor Co., Inc. 21001 State Route 739, Raymond, Ohio 43067-9705					
Full Name of Third Assignor Jason Travis MCLEOD	Assignor's Signature	Date			
Address: c/o American Honda Motor Co., Inc. 21001 State Route 739, Raymond, Ohio 43067-9705					
Full Name of Fourth Assignor Norbert L. KUKTA	Assignor's Signature Valut / hubots	Date Aug 1, 2023			
Address:  c/o American Honda Motor Co., Inc. 21001 State Route 739, Raymond, Ohio 43067-9705					
NAMES OF ADDITIONAL INVENTORS ATTACHED [ ] YES [X] NO					

KENEALY VAIDYA LLP

PATENT REEL: 064463 FRAME: 0441

**RECORDED: 08/02/2023**